

PATENT ABSTRACTS OF JAPAN

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(54) SEMICONDUCTOR DEVICE TEST PROBE CARD

(57)Abstract:

PURPOSE: To provide a probe card which is so improved as to be directly aligned with a tested semiconductor device of multiple pin structure using the pads of the semiconductor device, where the probe card is used to carry out probing test of a semiconductor device of multiple pin structure provided with pads located not only at the peripheral part but also in the inside of a semiconductor chip.

CONSTITUTION: A semiconductor device test probe card is used for the test of a semiconductor device 3, where pads 6 are provided to the peripheral region of a substrate 4 provided with an opening 5 at its center, the one ends of probes 10 are connected to one of the pads 6, and the other ends of the probes 10 are exposed at the opening 5, where the probes 10 are provided in multilayer brought into contact with pads 11 of a semiconductor device 3 of multiple pin structure provided with the pads inside it to test the semiconductor device 3 concerned. The probes 10 are so structured as to be provided to a region except an upper region located above aligning pads except probes which come into contact with aligning pads provided to a part of the periphery of the semiconductor device 3 of multiple pin structure.

